

IN THE SPECIFICATION

Please replace the paragraph on page 3, lines 15-22, with the following paragraph:

1. ~~1. A~~ In one embodiment a positive photosensitive resin composition comprising an alkali-soluble resin, a 1,2-quinone diazide compound, a crosslinking compound having at least two epoxy groups and a surfactant, wherein the above alkali-soluble resin is a copolymer comprising a carboxyl group-containing acrylic monomer, a hydroxyl group-containing acrylic monomer and an N-substituted maleimide as essential components.

Please replace the paragraph on page 3, line 23 through page 4, line 3, with the following paragraph:

2. ~~The~~ In another embodiment the positive photosensitive resin composition ~~according to 1, which~~ comprises the 1,2-quinone diazide compound in an amount of from 5 to 100 parts by weight, the crosslinking compound having at least two epoxy groups in an amount of from 1 to 50 parts by weight, and the surfactant in an amount of from 0.01 to 2 parts by weight, based on 100 parts by weight of the alkali-soluble resin component.

Please replace the paragraph on page 4, lines 4-16, with the following paragraph:

3. ~~The positive photosensitive resin composition according to 1 or 2, wherein~~ In another embodiment the number average molecular weight of the copolymer is from 2,000 to 9,000.

4. ~~The positive photosensitive resin composition according to any one of 1 to 3, wherein~~ In another embodiment the copolymer comprises the carboxyl group-containing acrylic monomer in an amount of from 5 to 30 mol%, the hydroxyl group-containing acrylic monomer in an amount of from 5 to 50 mol% and the N-substituted maleimide in an amount of from 10 to 70 mol% as monomer components.

~~5. The positive photosensitive resin composition according to any one of 1 to 4, wherein~~  
In another embodiment the surfactant is a fluorine type surfactant.

Please replace the paragraph on page 4, lines 17-21, with the following paragraph:

~~6. A~~ The invention includes a method for forming a pattern, which uses ~~the~~ one or more  
of the other embodiments of the positive photosensitive resin composition ~~as defined in any~~  
~~one of 1 to 5~~ wherein the postbake conditions are charged to arbitrarily form a pattern having  
a semicircular or trapezoidal section.